

BCR12KM-12LB

Triac

Medium Power Use

REJ03G0325-0100

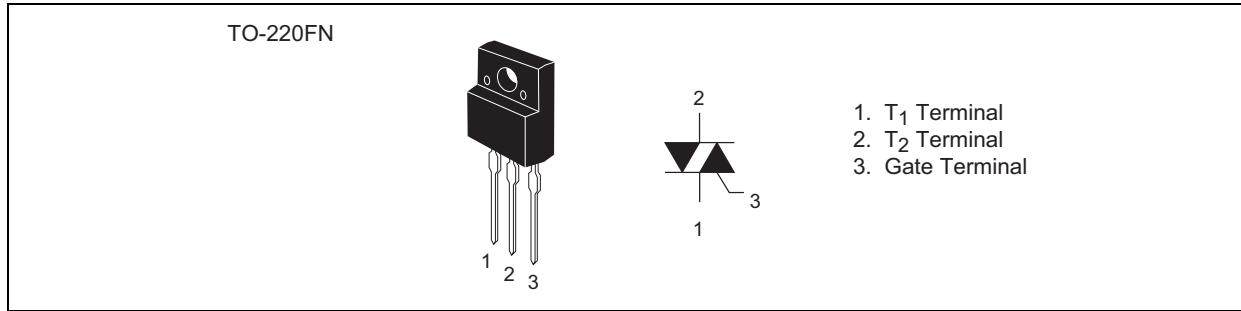
Rev.1.00

Aug.20.2004

Features

- $I_T(\text{RMS}) : 12 \text{ A}$
- $V_{\text{DRM}} : 600 \text{ V}$
- $I_{\text{FGTI}}, I_{\text{RGTI}}, I_{\text{RGTH}} : 30 \text{ mA} (20 \text{ mA})^{\text{Note5}}$
- Viso : 2000 V
- The product guaranteed maximum junction temperature 150°C.
- Insulated Type
- Planar Passivation Type
- Refer to the recommended circuit values around the triac before using.

Outline



Applications

Switching mode power supply, washing machine, copying machine, motor control, heater control, and other general purpose control applications

Maximum Ratings

Parameter	Symbol	Voltage class		Unit
		12		
Repetitive peak off-state voltage ^{Note1}	V_{DRM}	600		V
Non-repetitive peak off-state voltage ^{Note1}	V_{DSM}	720		V

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	$I_{T\text{ (RMS)}}$	12	A	Commercial frequency, sine full wave 360° conduction, $T_c = 102^\circ\text{C}$
Surge on-state current	$I_{T\text{SM}}$	120	A	60Hz sinewave 1 full cycle, peak value, non-repetitive
I^2t for fusing	I^2t	60	A^2s	Value corresponding to 1 cycle of half wave 60Hz, surge on-state current
Peak gate power dissipation	P_{GM}	5	W	
Average gate power dissipation	$P_G(\text{AV})$	0.5	W	
Peak gate voltage	V_{GM}	10	V	
Peak gate current	I_{GM}	2	A	
Junction temperature	T_j	-40 to +150	$^\circ\text{C}$	
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$	
Mass	—	2.0	g	Typical value
Isolation voltage	V_{iso}	2000	V	$T_a = 25^\circ\text{C}$, AC 1 minute, $T_1 \cdot T_2 \cdot G$ terminal to case

Notes: 1. Gate open.

Electrical Characteristics

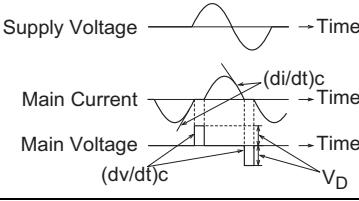
Parameter	Symbol	Minimum Characteristics Value			Unit	Test conditions
		Min.	Typ.	Max.		
Repetitive peak off-state current	I_{DRM}	—	—	2.0	mA	$T_j = 150^\circ\text{C}$, V_{DRM} applied
On-state voltage	V_{TM}	—	—	1.6	V	$T_c = 25^\circ\text{C}$, $I_{TM} = 20$ A, Instantaneous measurement
Gate trigger voltage ^{Note2}	I	V_{FGT_I}	—	—	V	$T_j = 25^\circ\text{C}$, $V_D = 6$ V, $R_L = 6$ Ω , $R_G = 330$ Ω
	II	V_{RGTI}	—	—	V	
	III	$V_{RGTI_{III}}$	—	—	V	
Gate trigger current ^{Note2}	I	I_{FGT_I}	—	—	30 ^{Note5} mA	$T_j = 25^\circ\text{C}$, $V_D = 6$ V, $R_L = 6$ Ω , $R_G = 330$ Ω
	II	I_{RGTI}	—	—	30 ^{Note5} mA	
	III	$I_{RGTI_{III}}$	—	—	30 ^{Note5} mA	
Gate non-trigger voltage	V_{GD}	0.2/0.1	—	—	V	$T_j = 125^\circ\text{C}/150^\circ\text{C}$, $V_D = 1/2$ V_{DRM}
Thermal resistance	$R_{th(j-c)}$	—	—	3.3	$^\circ\text{C/W}$	Junction to case ^{Note3}
Critical-rate of rise of off-state commutating voltage ^{Note4}	$(dv/dt)c$	10/1	—	—	V/ μ s	$T_j = 125^\circ\text{C}/150^\circ\text{C}$

Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

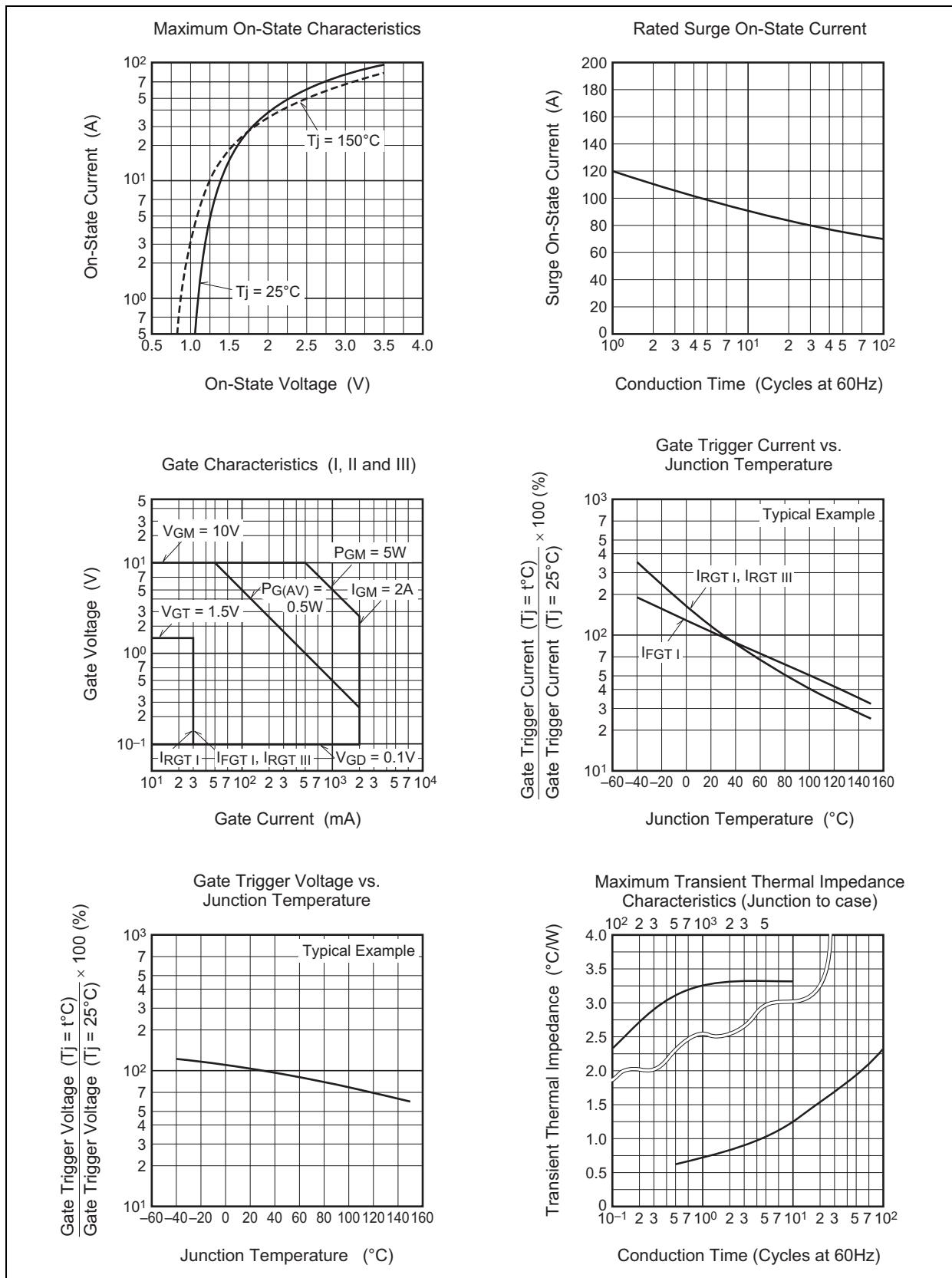
3. The contact thermal resistance $R_{th(j-c)}$ in case of greasing is 0.5°C/W .

4. Test conditions of the critical-rate of rise of off-state commutating voltage is shown in the table below.

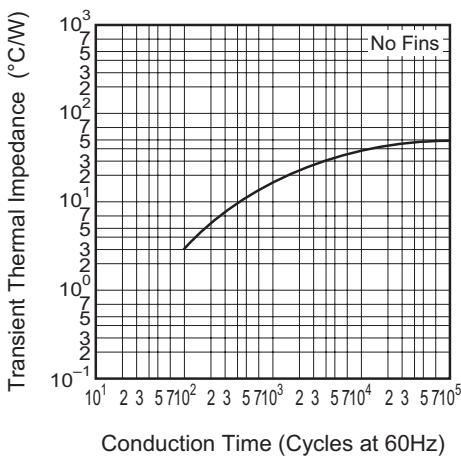
5. High sensitivity ($I_{GT} \leq 20$ mA) is also available. (I_{GT} item: 1)

Test conditions	Commutating voltage and current waveforms (inductive load)
1. Junction temperature $T_j = 125^\circ\text{C}/150^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)c = -6$ A/ms 3. Peak off-state voltage $V_D = 400$ V	

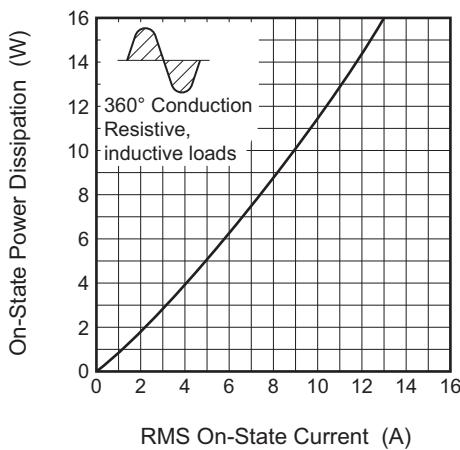
Performance Curves



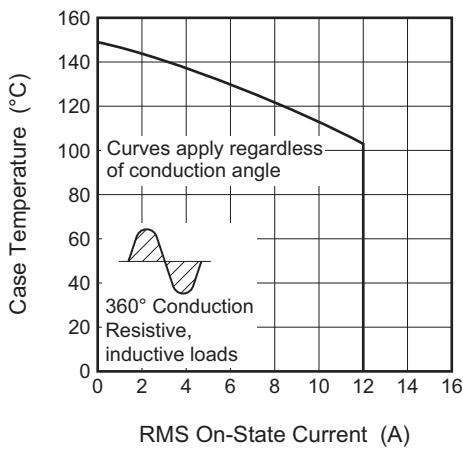
Maximum Transient Thermal Impedance Characteristics (Junction to ambient)



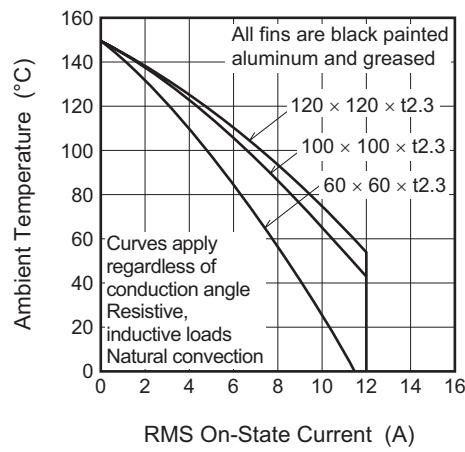
Maximum On-State Power Dissipation



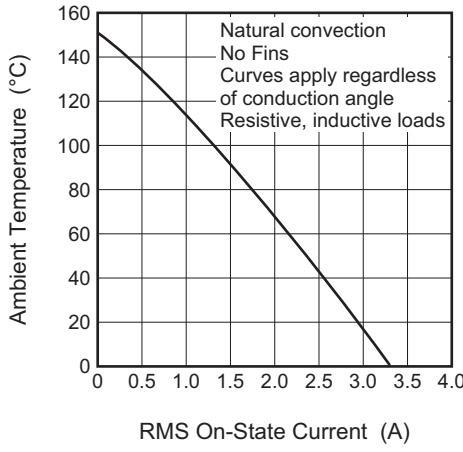
Allowable Case Temperature vs. RMS On-State Current



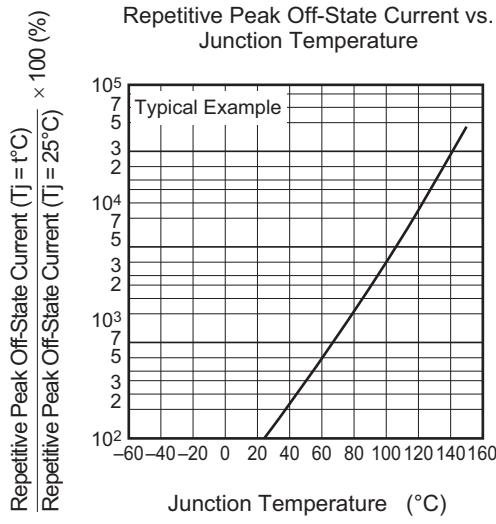
Allowable Ambient Temperature vs. RMS On-State Current

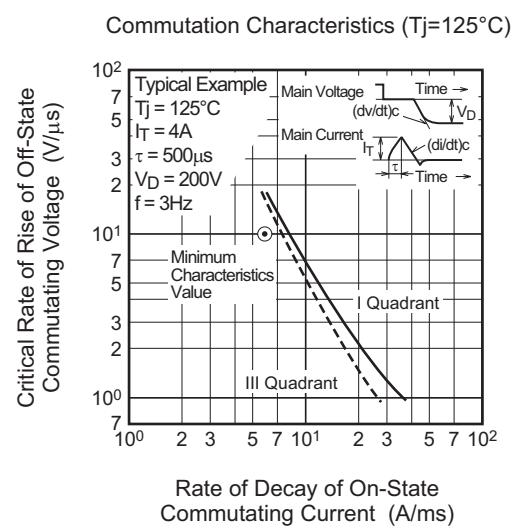
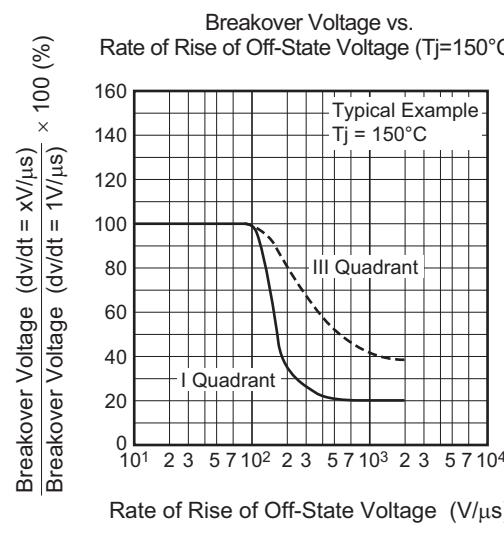
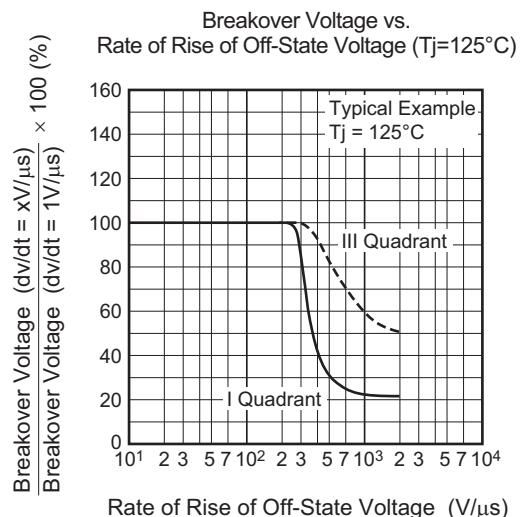
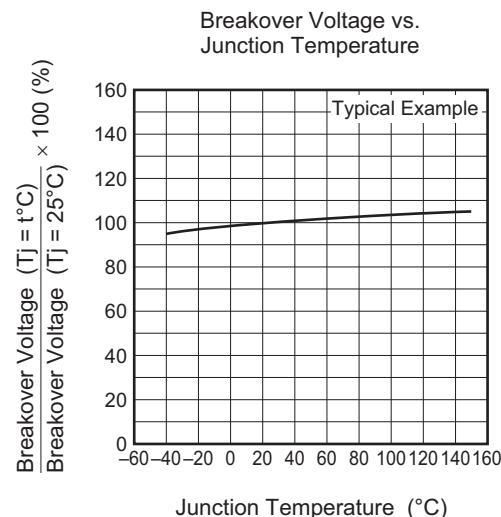
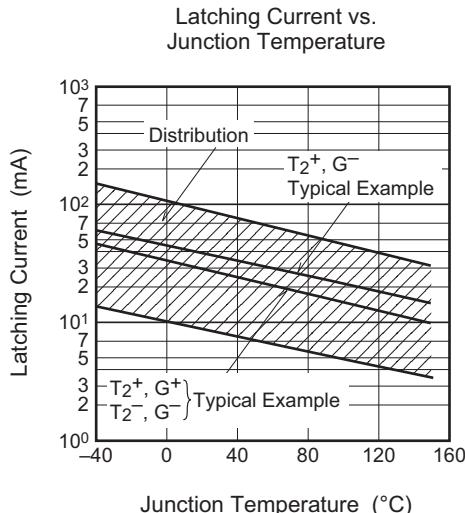
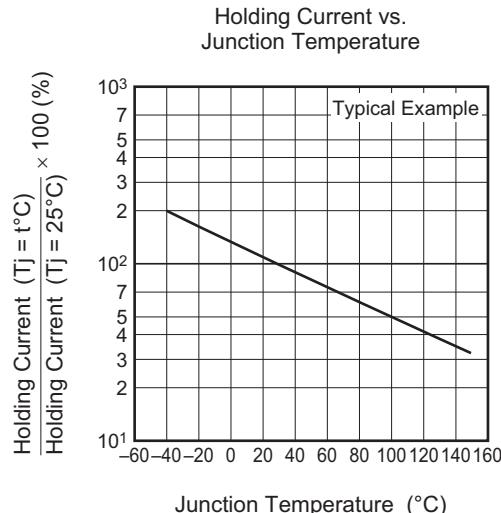


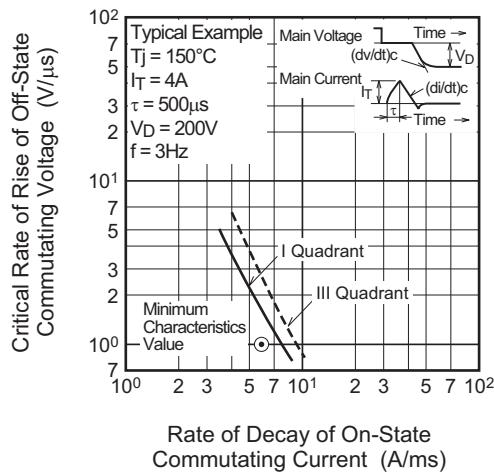
Allowable Ambient Temperature vs. RMS On-State Current



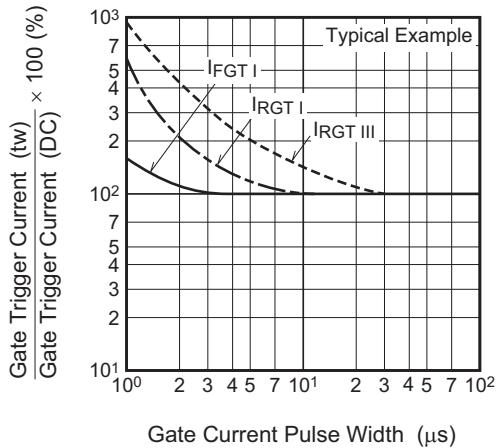
Repetitive Peak Off-State Current vs. Junction Temperature



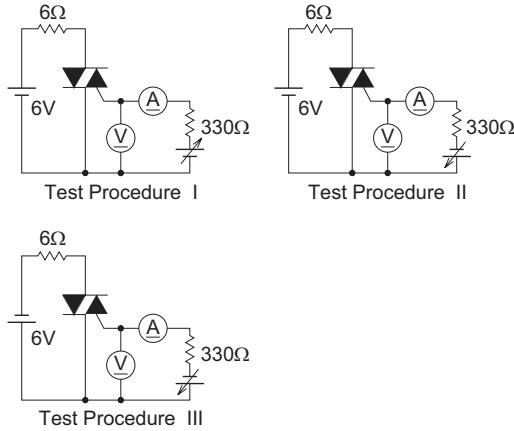


Commutation Characteristics ($T_j=150^\circ\text{C}$)

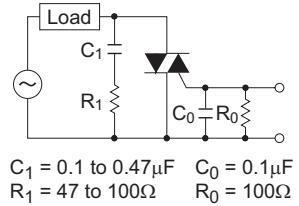
Gate Trigger Current vs. Gate Current Pulse Width



Gate Trigger Characteristics Test Circuits

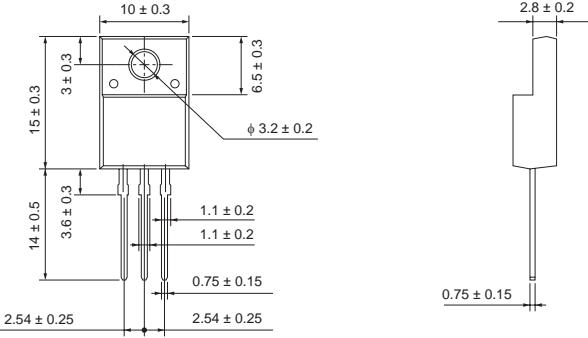


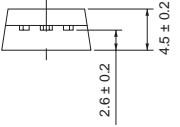
Recommended Circuit Values Around The Triac



Package Dimensions

TO-220FN				
EIAJ Package Code	JEDEC Code	Mass (g) (reference value)	Lead Material	
—	—	2.0	Cu alloy	



Symbol	Dimension in Millimeters		
	Min	Typ	Max
A	—	—	—
A ₁	—	—	—
A ₂	—	—	—
b	—	—	—
D	—	—	—
E	—	—	—
e	—	—	—
x	—	—	—
y	—	—	—
y ₁	—	—	—
ZD	—	—	—
ZE	—	—	—

Note 1) The dimensional figures indicate representative values unless otherwise the tolerance is specified.

Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Plastic Magazine (Tube)	50	Type name	BCR12KM-12LB
Lead form	Plastic Magazine (Tube)	50	Type name – Lead forming code	BCR12KM-12LB-A8

Note : Please confirm the specification about the shipping in detail.

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